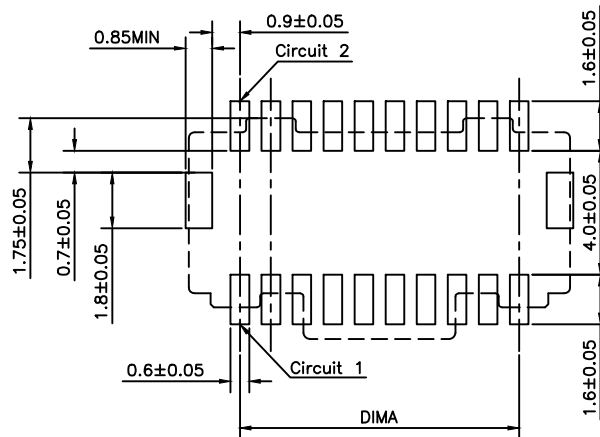
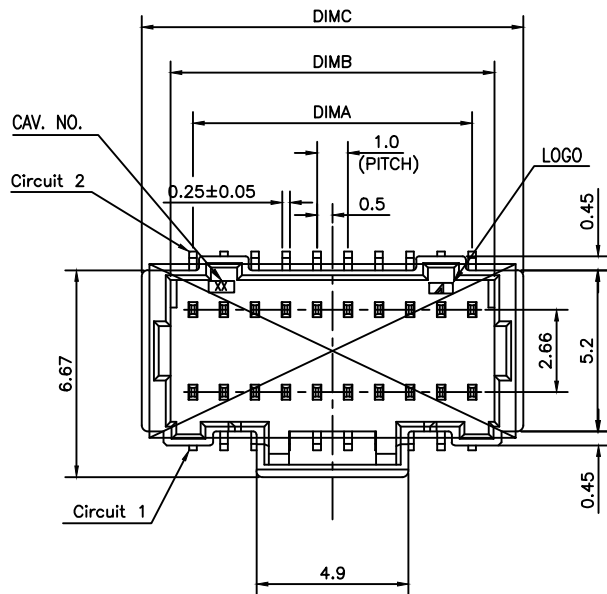




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

NOTES:

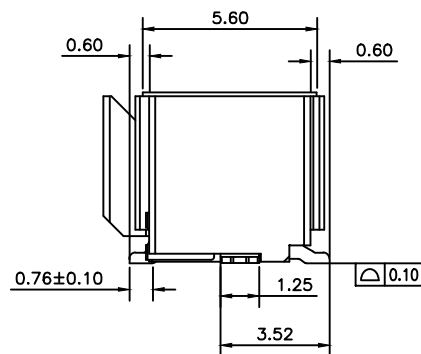
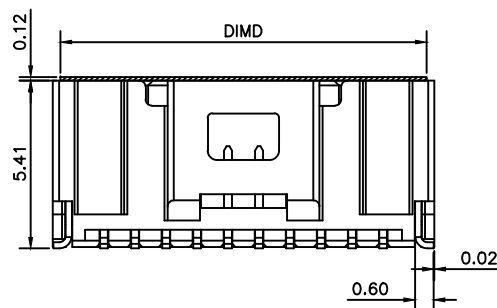
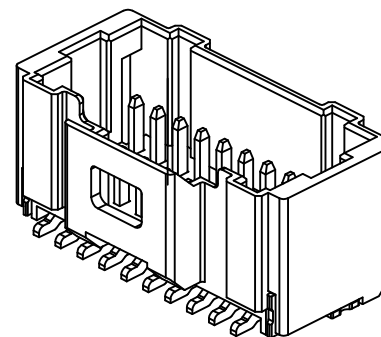
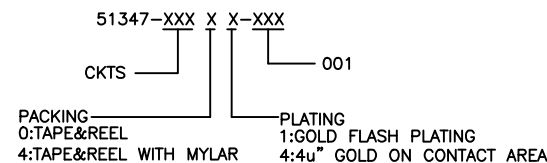
1. MATERIAL:

- 1.1 HOUSING: HALOGEN FREE PA4T, HIGH TEMP., UL94V-0.
- 1.2 CONTACT: PHOSPER BRONZE C5191-H
- 1.3 FITTING NAIL: BRASS C2680-H

2. FINISH:

- 2.1 CONTACT: 50u" MIN. NICKEL UNDERPLATING OVERALL.
1:GOLD FLASH ON CONTACT AND SOLDER AREA
4:4u"GOLD ON CONTACT AND SOLDER AREA
- 2.2 FITTING NAIL: 50u" MIN. NICKEL UNDERPLATING OVERALL.
N:80u" MIN. MATTE TIN PLATING
3. REFLOW SOLDER CAPABLE TO 260°C
PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-51347-XXXXX-XXX
5. PACKAGE PLS. REFER TO 51347-XXXXX-XX-TRP.
6. PART NUMBER



CKTS	DIM A	DIM B	DIM C	DIM D (M/Y SIZE)
20	9.0	10.45	12.30	11.80
24	11.0	12.45	14.30	13.80
30	14.0	15.45	17.30	13.80
40	19.0	20.45	22.30	21.80
50	24.0	25.45	27.30	26.80

QUALITY SYMBOLS		DRAWN BY		DATE		ACES ELECTRONICS	
MAJOR 		Hualin		22/06/09			
CRITICAL 		CHECKED BY		DATE		TITLE	
GENERAL TOLERANCES (UNLESS SPECIFIED)		BRAVE		22/06/09			
		APPROVED BY		DATE			
		BRAVE		22/06/09			
X. ±0.5						1.0mm pitch WTB Wafer Conn. SMT D/R S/T Type	
.X ±0.25							
.XX ±0.15							
.XXX ±0.1							
ANGLES ±2°							
		UNITS		SIZE	RFQ NO.	NA	
		mm		A4			
		SCALE	SHEET NO.	REV	PART NO.	SEE NOTES	
		1 : 1	1 OF 1	D			
					DWG NO.	51347-XXXXX-XXX	